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**April 2015** 

## FGA6560WDF 650 V, 60 A Field Stop Trench IGBT

#### **Features**

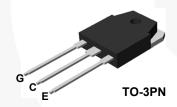
- Maximum Junction Temperature: T<sub>J</sub> =175°C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 1.8 \text{ V(Typ.)} @ I_C = 60 \text{ A}$
- 100% of the Parts Tested for I<sub>LM</sub>(1)
- · High Input Impedance
- · Fast Switching
- · RoHS Compliant

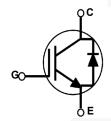
#### **General Description**

Using novel field stop IGBT technology, Fairchild's new series of field stop 3<sup>rd</sup> generation IGBTs offer the optimum performance for welder and industrial applications where low conduction and switching losses are essential.

#### **Applications**

- · Welder and Industrial Application
- · Power Factor Correction





### **Absolute Maximum Ratings**

Symbol	Description		FGA6560WDF	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		650	V
M	Gate to Emitter Voltage		± 20	V
$V_{GES}$	Transient Gate to Emitter Voltage		± 30	V
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	120	Α
'C	Collector Current	@ T <sub>C</sub> = 100°C	60	Α
I <sub>LM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C	180	Α
I <sub>CM (2)</sub>	Pulsed Collector Current		180	Α
l <sub>F</sub>	Diode Forward Current	@ T <sub>C</sub> = 25°C	60	Α
'F	Diode Forward Current	@ T <sub>C</sub> = 100°C	30	А
I <sub>FM (2)</sub>	Pulsed Diode Maximum Forward Curren	t	120	Α
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	306	W
' D	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	153	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +175	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

#### Notes

- 1.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  =180 A,  $R_{G}$  = 62  $\Omega$ , Inductive Load
- 2. Repetitive rating: Pulse width limited by max. junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	FGA6560WDF	Unit	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case, Max.	0.49	°C/W	
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case, Max.	1.75	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W	

# Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA6560WDF	FGA6560WDF	TO-3PN	Tube	-	-	30

## Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1 mA	650	-	-	V
ΔBV <sub>CES</sub> / ΔΤ <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	I <sub>C</sub> = 1 mA, Reference to 25°C	-	0.6	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	250	μΑ
I <sub>GES</sub>	G-E Leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0 V	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 60 mA, V <sub>CE</sub> = V <sub>GE</sub>	4.1	5.6	7.6	V
()		I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V	-	1.8	2.3	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 175°C	-	2.3	-	V
Dynamic C	Characteristics					
C <sub>ies</sub>	Input Capacitance		-	2419	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	82	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	- 1 - 11VII 12	-	31	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-/	25.6	-	ns
t <sub>r</sub>	Rise Time		-	67.2	- /	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	71	/	ns
t <sub>f</sub>	Fall Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	-	22	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	2.46	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.52	- //	mJ
E <sub>ts</sub>	Total Switching Loss		-	2.98	-	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	22.4	- \	ns
t <sub>r</sub>	Rise Time		-	63.2	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 60 A,	-	77	-	ns
t <sub>f</sub>	Fall Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	-	22	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 175°C	-	3.19	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.71	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	3.90	-	mJ

## **Electrical Characteristics of the IGBT** (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Qg	Total Gate Charge		-	84	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	15	-	nC
Q <sub>gc</sub>	Gate to Collector Charge		-	32	-	nC

## Electrical Characteristics of the Diode T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		Test Conditions			Min.	Тур.	Max	Unit	
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =	30 A		T <sub>C</sub> = 25°C	-	1.8	2.3	V	
				Ī	T <sub>C</sub> = 175°C	-	1.7	-	'	
E <sub>rec</sub>	Reverse Recovery Energy				T <sub>C</sub> = 175°C	-	233	-	uJ	
t <sub>rr</sub>	Diode Reverse Recovery Time	I <sub>F</sub> = 30 A, dI <sub>F</sub> /dt = 200 A/μs	Ī	T <sub>C</sub> = 25°C	/ -	110	-	ns		
			30 Λ, αι <sub>Ε</sub> /αι – 200 <i>Α</i> /μο	Ī	T <sub>C</sub> = 175°C	-	271	-	''	
Q <sub>rr</sub>	Diode Reverse Recovery Charge			Ī	T <sub>C</sub> = 25°C	-	400	-	nC	
αn	Disac Neverse Nesertary Change			Ī	T <sub>C</sub> = 175°C	-	1740	-		

Figure 1. Typical Output Characteristics

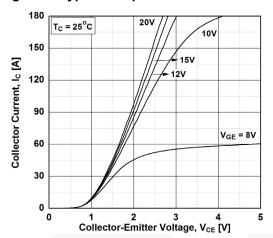


Figure 3. Typical Saturation Voltage Characteristics

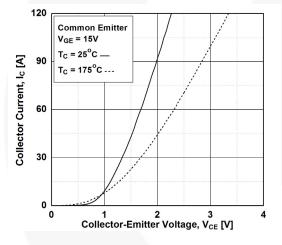
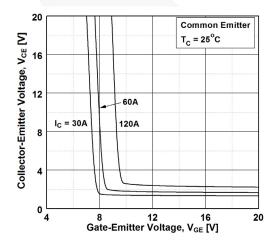


Figure 5. Saturation Voltage vs. V<sub>GE</sub>



**Figure 2. Typical Output Characteristics** 

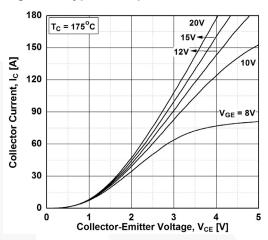


Figure 4. Saturation Voltage vs. Case

Temperature at Variant Current Level

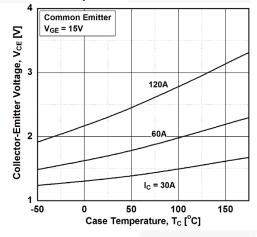


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

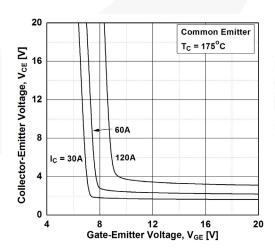


Figure 7. Capacitance Characteristics

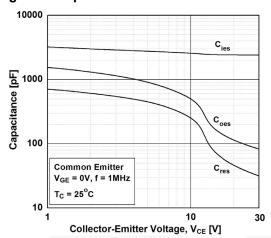


Figure 9. Turn-on Characteristics vs.
Gate Resistance

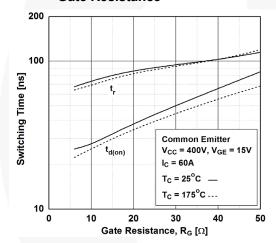


Figure 11. Switching Loss vs.
Gate Resistance

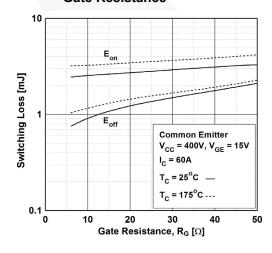


Figure 8. Gate charge Characteristics

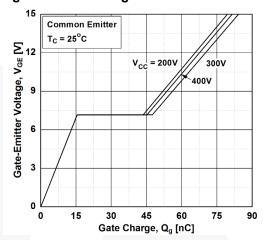


Figure 10. Turn-off Characteristics vs. Gate Resistance

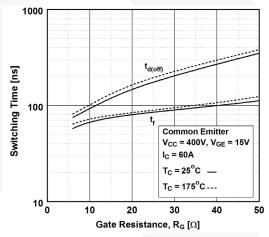


Figure 12. Turn-on Characteristics vs. Collector Current

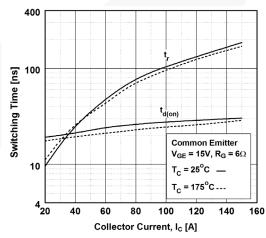


Figure 13. Turn-off Characteristics vs. Collector Current

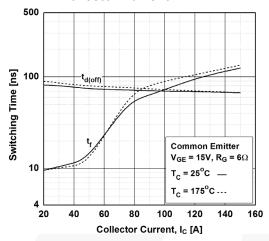


Figure 14. Switching Loss vs. Collector Current

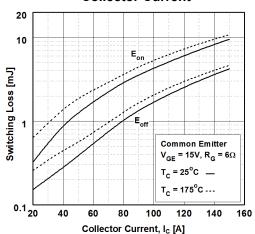


Figure 15. Load Current Vs. Frequency

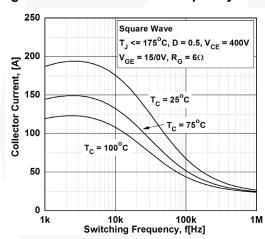


Figure 16. SOA Characteristics

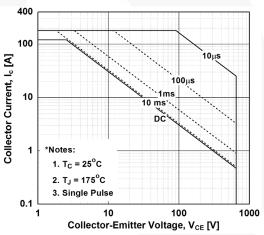


Figure 17. Forward Characteristics

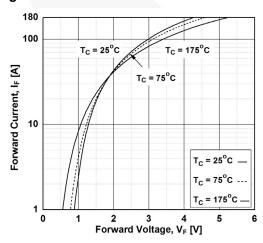


Figure 18. Reverse Recovery Current

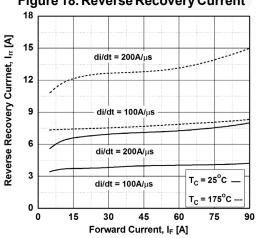


Figure 19. Reverse Recovery Time

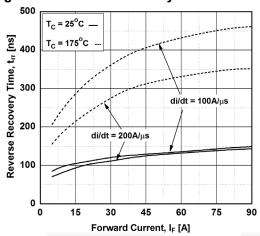


Figure 20. Stored Charge

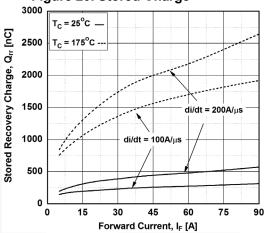


Figure 21. Transient Thermal Impedance of IGBT

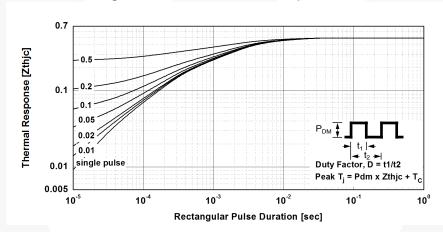
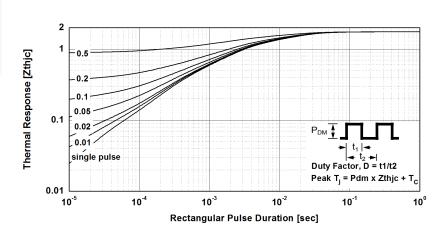
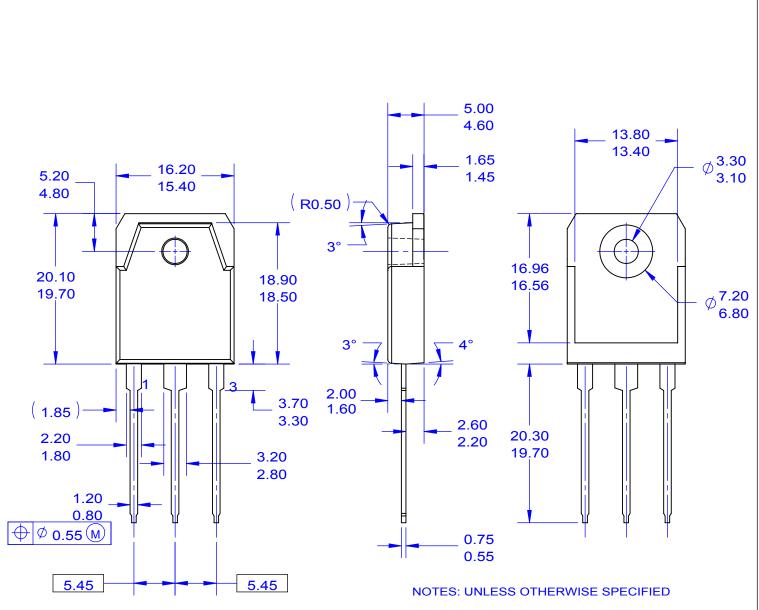
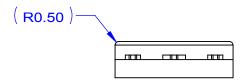


Figure 22. Transient Thermal Impedance of Diode







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- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
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